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(54) CONFIGURABLE MICRO HEAT PIPE (MHP) AND MICROCHANNEL FOR IMPROVED COOLING OF GLASS CORE SUBSTRATE

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(57)ABSTRACT

Embodiments disclosed herein include electronic packages. In an embodiment, the electronic package comprises a core with a first surface and a second surface opposite from the first surface, and where the core comprises glass. In an embodiment, a channel is disposed into the first surface of the core, and a lid is provided over the channel. In an embodiment, the lid seals the channel between a first end and a second end of the channel.

